# **STATUS OF TOTEM**

# Progress summary report for the November 2008 RRB

### **Introduction**

The TOTEM experiment has been described in detail in the document presented to the October 2007 RRB. Therefore in this document, we concentrate on the progress made in 2008 and the expected final installation of the complete experiment. During the year 2008, the three subdetectors have been tested with the final electronics and for each subdetector, a production line with final tests has been established. A detailed plan is attached.

The aim is to install the complete TOTEM experiment before summer 2009 with one exception: the Roman Pots at the high radiation stations (147 m from the IP) will only be partially equipped in order to gain preliminary experience with the radiation and to save some Silicon detectors for the case of unexpectedly high radiation levels.

We envisage that the TOTEM experiment will operate continuously as soon as the LHC begins running. The experience gained during the low luminosity start-up phase will enable us to use efficiently the short duration runs with our specialized optics, which will hopefully be commissioned during 2009.

### The T1 CSC Telescope

The T1 inelastic telescope is designed to detect the passage of charged particles in the pseudorapity range  $3.1 < |\eta| < 4.7$ . It will be installed, on either side of the interaction point, in the space between the LHC beam pipe and the inner envelope of the CMS endcaps. Each "arm" of the telescope consists of five layers of wire chambers with cathode strip read-out (CSC). Each chamber, of trapezoidal shape, covers approximately 60° in azimuth, so that 6 chambers are needed to complete a layer; because of the geometry and space constraints of the detector, overall 10 different shapes are required. Each arm is split vertically into two "half-arms", with independent support structure, services and read-out chains.

The CSC are assembled at PNPI in Gatchina, Russia. Out of 70 chambers needed in total (60 + 10 spares), 62 have been completed. For 51 of them the acceptance tests performed at PNPI have been successfully repeated at CERN.

The read-out electronics has been fully developed and successfully tested. It includes the anode front-end cards (AFEC: 10 different types), the cathode front-end cards (CFEC: fully digital read-out) and the concentrator boards (ROC). The first production series allowed to equip one "half-arm" (1/4 of the total); production of the remaining boards will start soon. About one third of the VFAT front-end chips and of the small PCB hosting them have been received the rest will follow in time. All low voltage and high voltage power supplies (mainframes and modules) have been delivered.

A storage/test/assembling area has been set up at building 188 at CERN. Cosmic rays tests are currently undergoing, with the final read-out chain and power supplies, and a DAQ system using the same hardware as the final one. One half-arm of the detector has been fully assembled, with complete local cabling and piping. All pieces making up the support structure for the two arms have been produced in Genova and assembly-tested with CSC mock-ups.

 
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Table 1: Planning for the T1 detector

Table 1 shows the planning for the production and the final tests of the complete T1 detector, including electronics and the mechanical structures. After having passed the cosmic ray tests, the detector will be ready in April 2009 for installation into the CMS environment.

### The T2 GEM Telescope

The T2 telescopes are installed in the forward shielding of CMS between the vacuum chamber and the inner shielding of the HF calorimeter. In each arm, 20 semi-circular GEM planes are interleaved on both sides of the vacuum chamber to form 10 detector planes with full azimuthal coverage. The gaseous electron multipliers (GEM) detectors were chosen because of their high rate capability, good spatial resolution, robust mechanical structure and their excellent ageing characteristics.

All GEM chambers were produced in Helsinki in the clean rooms of the Detector Laboratory where a dedicated assembly line was set up. The production of 50 GEMs (40 for T2 plus 10 spares) terminated about a year ago. An extensive effort, partly automated, ensured highest quality control. It included leakage current measurements of the GEM foils, optical inspection of the foils and search for broken or short-circuited strips/pads on the readout board, and finally a  $^{55}$ Fe source test.

During summer 2008 the readout electronics has been finalized and tested. The first quarter of the T2 telescope was assembled and fully equipped with electronics to be systematically tested in the SPS beam line H8 where also cabling and shielding were optimized with respect to noise reduction. These extensive tests were a common effort of the Pisa/Siena, Helsinki and CERN groups. After some optimization, the operation of the GEM chambers was fully satisfactory and according to expectations. During August 2008, this first quarter telescope was then installed in IP5 in view of obtaining first results from LHC collisions. However, these chambers have now to be temporarily removed during the coming shutdown in order to stiffen its mechanical structure, which has shown some instability due to the unexpected strong magnetic field in the forward region of CMS.

The second quarter is presently assembled in the TOTEMINO facility on the H8 line, with tests done with cosmic rays due to the lack of beam. In the meanwhile, the third and fourth T2 quarters chambers are being fully assembled and tested in their final configuration in Helsinki. The final mechanical assembly with the readout electronics of the second telescope will be carried out at CERN. In compliance with the CMS schedule, the complete T2 telescope, fully instrumented, is expected to be installed in IP5 between January and March 2009, as shown in the planning in Table 2.

Table 2: Planning of the T2 telesope



### **Roman Pot detectors**

All Totem Roman Pot stations have been mounted and integrated into the outcoming beam pipes on both sides of IP5. The cabling and the piping are completed at the points at 220 m away from the IP. For the other stations it will be finished before the end of 2008.

We are now in the process of installing the detector packages in the Roman Pots. Each detector package is made of 10 precisely mounted planes of hybrids containing one edgeless silicon sensor and four VFAT readout/trigger chips in a secondary vacuum. A common motherboard reads the data and feeds them through a gastight vacuum flange to the outside DAQ. Two detector packages have already been installed at the farest stations at 220m away from IP5 at each side. This has allowed to complete the commissioning of the cooling station which has been installed centrally in IP5 to serve the Roman Pot systems at both sides. It has shown the expected results: a temperature of -33°C in the pot without heat load, corresponding to about -20°C at full load.

The mounting of the detector packages follows a detailed sequence of characterization and quality control between the different assembly steps. These activities require the use of the PH DT Silicon Detector facility for testing the Si sensors, the TOTEM Test Platforms for testing the VFAT chips (2 setups are now available close to the bonding Lab in the former CMS Tracker Test Infrastructure), the chip gluing and the bonding machines of the PH DT group and the Computer Measuring Machine, also available in the bonding lab, to precisely control and measure the position of the sensors on the hybrids. The assembly of the detector package is completed with the precise mounting of the ten hybrids in a stack equipped with capillaries and cooling pipes and the "champignon" vacuum flange. For the test of the separated Motherboard and its mezzanine cards a specific setup based on VME electronics has been developed and is now available in the TOTEM Lab.

Before installation in the tunnel, each detector package has to be tested in the H8 beam area where a reduced version of the final DAQ and Data monitoring system allows to test the full functionality of the detectors and the front end electronics with cosmic rays replacing the originally foreseen SPS beam. During these tests the detector packages are hosted in vacuum in a prototype pot, cooled down with the "H8 Cooling Plant" and controlled with a mini-DCS developed on purpose for H8 to run in the same environmental conditions than the ones foreseen for the running of the experiment.

With the full VFAT chip production and all needed Si sensors delivered, hybrids are mounted and the detector packages are assembled as the hybrid boards become available. For the time being the pots 3, 4 and 5 are being assembled, following the plan to produce the 12 detector packages needed to equip all pots of the RP Stations at 220m by the end of March and to complete the production for the summer 2009. The planning for the production of the Roman Pot Detector packages for the stations at 220m is shown in Table 3 together with a detailed production sequence for Pot 4.

 
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Table 3: Planning for the production and test of the next pots to complete the installation of the stations at 220m

### **Electronics**

Table 4 shows the production and test schedule of all printed circuit boards for the TOTEM experiment.

The three TOTEM sub-detectors are using the same front-end chip: the VFAT mounted on detector specific hybrids provides both tracking and fast trigger data. The on-detector cards (Roman Pot motherboard, ROC for T1 and 11<sup>th</sup> and horseshoe card for T2) link the hybrids with front end chips to the outside world. Both trigger and tracking data are optically transmitted to the counting room where they are received by the HOST board with opto-receiver mezzanines. The counting room hardware was a shared development: the CMS preshower group designed the opto-receiver mezzanine and TOTEM the HOST board. The data can be transferred by USB, VME and Slink (for CMS compatibility).

The prototypes of the on-detector cards have now been fully tested. The development of the required preliminary versions of firmware and software took much longer than expected which delayed the mass production now expected to be completed before Christmas. Some printed circuit boards (e.g. the repeater and optocoupler card), needed in a later stage for joint runs with CMS, are still in design.

In addition, it became clear that the motor control could not generate the interlock signals for beam dump in a sufficiently reliable way, and that new dedicated electronics had to be developed. After several discussions with the machine, specifications are now finalized and the design is almost completed.

Production problems have been encountered with several boards:

The Roman Pot hybrids showed a metallization problem on about one quarter of the full production. After careful inspections and discussions with the company the problem seems to be understood and a new production has been launched.

The production of the hybrids for T1 and T2 has a low yield, and consequently about 200 hybrids still need to be produced to be completed in January 2009.

The Coincidence Chip hybrid production failed due to a processing problem. The first batch of new hybrids is expected mid November, and the rest at the end of the year.

We have just been informed about a problem with the HOST board production which is shared with CMS. This board is the main board in the counting room for data acquisition and trigger generation. 51 out of 90 boards were delivered. The rest apparently failed electrical test after components mounting. Together with CMS we are investigating further.

The installation of counting room infrastructure progressed significantly: power supplies and VME crates have been installed. For the DCS, several boards and crates were developed, which are being cabled now.

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Table 4: Production and test schedule of all printed circuit boards for the TOTEM experiment.

### **Trigger and Data Acquisition**

The DAQ and Trigger functions and algorithms are being developed as an mixture of software and firmware components. To make sure that they integrate smoothly and meet the performance needed for TOTEM-specific runs, and to take into account by design the interoperability of TOTEM with CMS, a unified requirement and specification procedure has been set up.

Wherever possible in the software (like in the case of the FEC and TTC subsystems) TOTEM is reusing libraries and/or applications inherited from CMS, with additions and specific modifications. New software packages have been built to deal with specific TOTEM hardware (i.e. the TOTFED VME board).

VME crates have been installed in the underground counting room at IP5. The related front-end PCs are now connected and operational. Dedicated tools for detector testing and commissioning have been developed, with innovative solutions like LOCAL DAQ systems running out of virtual machines, easily re-distributable in the collaboration.

Procurement of the full set of event-builder computers and storage for LOCAL DAQ is complete. The cluster is presently under test, running an emulated DAQ system. Speed and reliability of the storage system are being assessed. LOCAL DAQ components are used at IP5 for detector commissioning.

The trigger system is based on the VFAT Sbit outputs. 8 bits from each VFAT are programmed to map a group of input with a fast OR output. The trigger hits defined here will be used to elaborate a raw tracking algorithm to be used for the trigger of the experiment. The RP and T2 detectors use an onboard trigger chip (CC) to perform a majority coincidence of the hits recorded between different planes of the detectors. T1 has a more complex geometry requiring a different approach for the tracking.

The trigger tracks from RP and T2 are sent to the counting room through optical links or electrical LVDS links for the 220m RP, while T1 send hits with the same hardware. Totem trigger in the counting room is using the same hardware of DAQ to simplify the design, but special algorithms are being developed for the local FPGAs.

The algorithms foreseen are based on combinatorial logic built with Look Up tables, requiring track counting and grouping on each detector. The information from each subdetector is combined in a special mezzanine card developed in Siena, that deliver the trigger information to the TTC system and in case of combined runs with CMS, provides the necessary information for a CMS/TOTEM trigger.

### **Installation and Commissioning**

It is foreseen that almost all TOTEM detectors will be installed before the end of the Winter shutdown. The required installation of cables, gas pipes, cooling and interlock systems is underway.

The installation of the detectors and related electronics in the Roman Pots in the tunnel needs about 1 day per detector package and should be done in the shadow of the work needed by the machine. Movements and cooling tests are foreseen as well as interlock studies.

The installation of the T1 and T2 telescopes has to be organised in close collaboration with CMS, respecting their installation schedules. Some open issues about the mechanical support structure have to be discussed and solved.

The TOTEM readout and trigger system, in a stand-alone mode, will be installed in IP5 rather soon to allow extensive commissioning of all detector parts. This includes also the important Detector Control Systems (DCS) and general counting room infrastructure.

### **Offline Software and Computing**

The TOTEM Offline Software, which includes simulation, reconstruction, calibration, alignment and analysis, is based on the CMSSW Framework. Due to the modular structure of the CMS software, the TOTEM related packages can be incorporated in it, allowing in the future a combined TOTEM/CMS detector simulation and analysis. The first release of the TOTEM Offline Software has been issued during summer 2008.

A more complete release is foreseen for the end of year 2008. It will include optimisation of the reconstruction algorithms and a preliminary simulation of the L1 Trigger response. At the beginning of 2009, there will be a production of simulated data based on this release. We will continue the development of analysis tools to facilitate data and physics analysis. The (track) reconstruction algorithms have been already tested, when available, with test beam data. The Calibration and Alignment chain, using the Conditions Database, needs to be developed. In 2009 the review and optimisation of the software will continue, following the commissioning of the detectors.

## **Physics**

The early LHC runs will be at low  $\beta^*$  with beams having reduced number of bunches and a lower number of protons per bunch giving TOTEM ample opportunities to make its first physics studies: high-|t| elastic scattering, high mass central and single diffraction and forward charged particle production in inelastic events. In addition, TOTEM is preparing for the possibility of shorter  $\beta^* = 90$  m runs aiming at an early total cross section measurement with 4-5 % relative precision as well as studies of soft diffraction at any diffractive mass value.

The physics group is preparing for analysis of TOTEM data from these runs in close collaboration with the offline software group. The offline software group is currently preparing the first release of the full TOTEM offline simulation and reconstruction chain by the end of the year. After a first large MC production during January 2009 of elastic and inelastic events at  $\beta^* = 2$  m, the time up to the LHC start will be devoted to developing efficient trigger selection criteria for the low  $\beta^*$  physics as well as preparing an analysis framework and different analysis tools (e.g. selection of proton candidates from Roman Pots and charged particle candidates from the T1 and T2 telescopes) for the physics analysis of the first data. Meanwhile, the group pursues systematic comparisons of different event generators, especially for the forward charged particle production in inelastic events. A detailed MC study of beam induced proton background in the Roman Pot detectors is also ongoing. Both studies are made in view of preparing for what could be expected to be seen in the first data.

### **Collaboration**

During this summer, the TOTEM Collaboration has welcomed as a new collaborator a group under the leadership of Prof. Tamas Csörgo from the Hungarian institute MTA KFKI RMKI. With its three active members, this new collaboration was fast integrated into TOTEM. The participation on the construction funds of 80 kCHF was used for the Silicon detector read-out, as agreed by the TOTEM Collaboration Board. They also contribute in the usual way to the M&O funds.

# Table 5: TOTEM Financial matrix

TOTEM - 12/09/2008 - Financial Matrix

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TOTEM	TOTAL	┢	CER		┡	INF		Ē	nland	F	Bru	nel	┢	Esto	nia	-	Prag	en		NSF		Ī	ungar	Y	C.Pro	jects	Γ
	MoU Proj F	aid M	oU Prc	oj Pai	Mo.	U Proj	Paid	NoN	Proj	Paid N	MoU F	<sup>o</sup> roj P	aid M	IN PI	roj Pa	aid Mc	U Pro	j Paio	d MoL	J Proj	Paid	MoU	Proj	Paid	NoU	u L	Out
1. ROMAN POTS	2476 3226	2970 1	702 24	50 23.	36																						
1.1 Roman Pot mechanics	651 865	845	456 6	18 5	86											-	95 2	47 24	17								
1.2 Movement	204 243	243	204 2	43 2	43																						
1.3 Beam position monitor	171 122	122	169 1	20 1.	20												2	2	2								
1.4 Detector mechanics	133 175	160	133 1	75 1	60																						
1.5 Silicon sensors	228 299	299	110 2	36 2	66						55	0	0						9	00 00		~					
1.6 Cooling	209 310	219	209 3	10 2	19																						
1.7 Electronics	554 643	562	175 2	60 2	28									40	42	42			32	4 24	4 165	0	80	80	15	17	17
<ol> <li>Power supplies and cables*</li> <li>Miscellaneous</li> </ol>	287 459 40 110	429 91	206 3 40 1	10 3	94	48	8	13	13	13				2	7	2	2	5	5	33	3 13	~					
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2. T1-CSC	1820 1742	1706	441 3	61 32	24	L	L									H	L									F	Γ
2.1 70 CSC Detectors	627 640	640			6	27 64	0 640								_												
2.2 Electronics	666 567	566	73	- 99	65 5(	11 41	6 416							_	_				7	0	0 70	0			15	15	15
2.3 Power supplies and cables	159 201	201	119	81	81	40 12 <sup>i</sup>	0 120																				
2.4 Supports and services	369 334	299	249 2	14 1	78	50 5	0 50												_						70	70	71
3. T2-GEM	1303 1521	1414																									
3.1 50 GEM Detectors	434 515	471						434	515	471					_												
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4. TEST SETUP	150 150	150		_	_							_															
4.1 Cables, power supplies & infrastr.	40 40	40	_	_	_									_											4	4	40
4.2 Electronics DAQ and computing	70 70	02		_	_										_										20	22	70
4.3 Pool rental & Consumables	40 40	40																							40	40	40
5. DAQ EVENT BUILDER	720 723	222																									
5.1 Readout column	170 137	137	_	_	÷	70 13	7 137							_													
5.2 Link into CMS DAQ**	500 500	0													_												
5.3 Online PC & storage	50 86	85				33 6.	39 6									_									17	17	16
11 TOTEN																											
IUIAL IUIEM	6470 7362	6462 2	2142 28	11 26	60 Z1.	33 220	7 2195	537	683	590	55	0	-	42	4	4	02 23	54 25	4 47	0 39	0 248	0	80	80	390	393	393
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\* Item 1.8 includes the redistributed Polish funds. The status of the compensation funds for those 127k is shown in the Credits sheet.

### **Construction Budget**

Table 5 summarizes the costs of the construction budget as stated in the original MoU together with the new projections and the contributions of the collaborating institutes. The contribution of the new Hungarian institute (80 kCHF) is foreseen for the RP electronics and reduces the load on NSF. The account for the Common Projects is balanced and will be closed now.

Some expenses could not be foreseen at the time of the MoU. For the final completion of the TOTEM detector, stringent safety and interlock systems connected to the LHC and some absolutely necessary improvements of the experiment's infrastructure are mandatory. These additional expenses of about 460 kCHF should be covered by CERN either because they are related to the CERN involvements (according to the MOU) or to the role of CERN as the host laboratory.